This document can handle board shapes up to 7.9in x 10in, although
our panel vendors top out at 7in x 10in.
To re-size the board shape, do the following:
Select lines on M1 Board Outline and delete (easy in single layer mode...shift+s)
Draw a rectangle using lines (example will be for a 4 x 6 board
Enter Place Line mode (keyboard pl)
keyboard jo to jump to origin, hit enter
keyboard jl to jump to location, set x to 6000, hit enter twice
keyboard jl to jump to location, set x to 6000 and y to 4000, hit enter twice
keyboard jl to jump to location, set x to 0 and y to 4000, hit enter twice
keyboard jo to jump to origin, hit enter
Hit ESC twice to exit place line mode

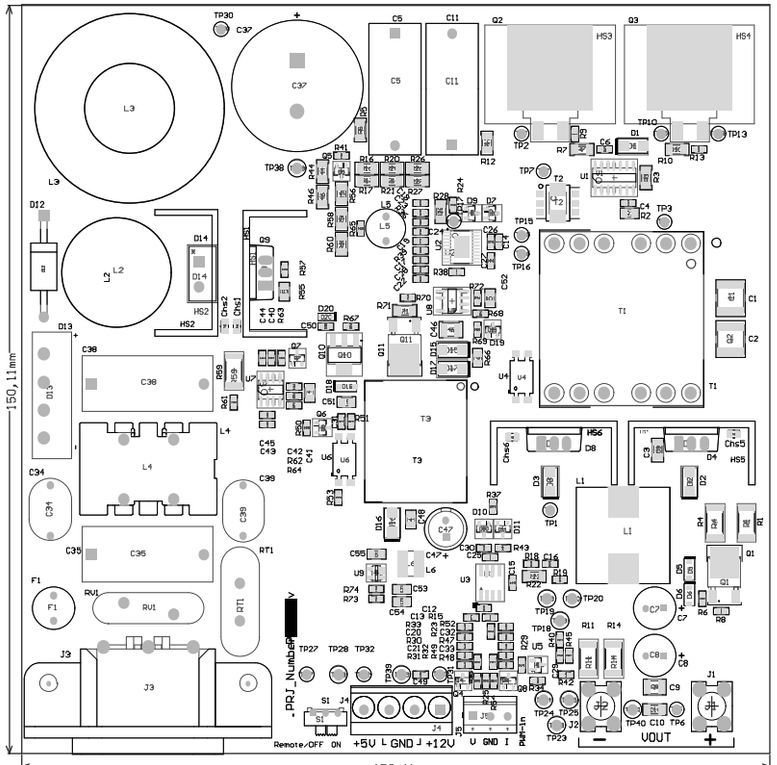
Select lines on M1 Board Outline
Menu Design\Board Shape\Define from Selected Objects (keyboard dsd)
To define a Keep-Out that mirrors the board outline:
Menu Design\Board Shape\Create Primitives From Board Shape (keyboard dsp)
Set the Keep-Out Layer as the layer, set width as preferred
Ensure Route Tool Outline is selected, hit enter

If you re-size the board, don't forget to move the drill table strings on the
Drill Drawing Layer...they should be just to the right of your board shape

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc

Layer Name	Barrier Thickness	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: .VariantName

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

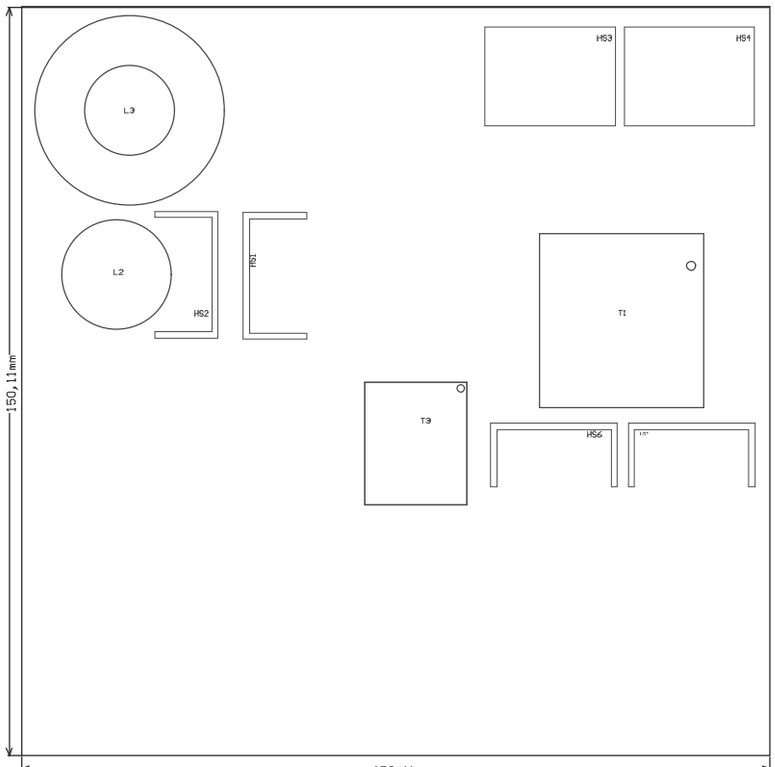
PROJECT TITLE: .PRJ_Title
DESIGNED FOR: .PRJ_Customer
FILE NAME: PMP10110 Rev_A PCB.PcbDoc

ENGINEER: .PRJ_Engineer
LAYOUT BY: .PCB_Layout
SCALE: 0.74
ALTIUM DESIGNER VERSION: 14.3.14.34663

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc

Layer Name	Gerber Documents	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: .VariantName

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: .PRJ_Title
DESIGNED FOR: .PRJ_Customer
FILE NAME: PMP10110 Rev_A PCB.PcbDoc

ENGINEER:	LAYOUT BY:
.PRJ_Engineer	.PCB_Layout
SCALE: 0.74	ALTIUM DESIGNER VERSION: 14.3.14.34663

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